PRODUCT CHANGE NOTICE

Alternate Manufacturing Site for Assembly of the Listed Intersil QFN Packaged Products

Refer to:
PCN12056

Date: July 10, 2012

July 10, 2012

To: Our Valued Intersil Customer

Subject: **Alternate Manufacturing Site for Assembly of the Listed Intersil QFN Packaged Products –** *Advanced Semiconductor Engineering - Chung-Li, Taiwan (ASECL)*

This notice is to inform you that Intersil is qualifying the Advanced Semiconductor Engineering (ASECL) facility as alternate site for assembly of the listed QFN (Quad Flat No-Lead) packaged products. Products manufactured at the ASECL facility will be assembled using copper bond wire. This action will expand current capabilities and capacities to optimize Intersil's ability to meet customer's delivery requirements. The product and site-specific qualification activities are in progress and expected to complete in September 2012.

Products affected:

ISL6277HRZ	ISL9492ERZ	ISL95833HRTZ	ISL95836HRTZ	ISL95838HRTZ
ISL6277HRZ-T	ISL9492ERZ-T	ISL95833HRTZ-T	ISL95836HRTZ-T	ISL95838HRTZ-T

The Advanced Semiconductor Engineering (ASECL) facility is ISO 9001:2008 and ISO/TS 16949:2009 certified and qualified as a supplier to Intersil for assembly of QFN packaged products with both copper and gold bond wire material. There will be no change in the mold compound series (G770), lead frame material, or package outline drawing (POD). Products assembled with copper bond wire are classified as moisture sensitivity level three (MSL 3 at 260°C per J-STD-020). As such, the listed products will be packed, labeled, and shipped as moisture sensitivity level three (MSL 3). The qualified material set combinations for assembly are as follows:

Key Items	CAS Current (ISL9492)	SCM Current (All Other Devices)	ASECL New (Alternate) (All Devices)
Mold Compound	Sumitomo EME-G770HC	Sumitomo EME-G770	Sumitomo EME-G770HJ
Die Attach	Hysol QMI 519	Ablebond A8290	Ablebond A8290
Bond Wire	1.3 mil Gold	1.2 mil Copper	1.2 mil Copper
Moisture Sensitivity Level	1	3	3
Device Marking - Site Code	F	M	W

The assembly qualification plan is designed using JEDEC and other applicable industry standards to confirm there is no impact to form, fit, function, or interchangeability of the product. A summary of the qualification plan is included for reference. The qualification results will be available for review upon completion by request. The remainder of the manufacturing operations (wafer fabrication, package level electrical testing, etc.) will continue to be processed to previously established conditions and systems.

Product affected by this change is identifiable via Intersil's internal traceability system. In addition, product assembled at ASECL may also be identified by the assembly site code (country of assembly) when marked on the devices. The site code for product assembled at ASECL with copper bond wire is "W".

Intersil will take all necessary actions to conform to agreed upon customer requirements and to ensure the continued high quality and reliability of Intersil products being supplied. Customers may expect to receive product assembled at either the current or the newly qualified sites beginning ninety days from the date or this notice or earlier with approval.

If you have concerns with this change notice, Intersil must hear from you promptly. Please contact the nearest Intersil Sales Office or call the Intersil Corporate line at 1-888-468-3774, in the United States, or 1-321-724-7143 outside of the United States.

Regards,

Jon Brewster

Jon Brewster
Intersil Corporation

PCN12056

CC: J. Touvell D. Decrosta D. Foster S. Nadarajah D. Grener P. Gaska D. Bruss
K. Stoddart B. Lee F. Tsng N. Anantharajah G. Liang J. Wei

PCN12056 – ASECL Reliability Qualification Plan

Stress/Conditions	Duration	ISL95836HRTZ		ISL95838HRTZ		ISL6277HRZ		ISL9492ERZ		ISL95833HRTZ	
		Lot 1	Lot2	Lot 1	Lot2	Lot 1	Lot 2	Lot 1	Lot2	Lot 1	Lot 2
High Temp Operating Life +125C	1000 Hours	0/40 Note 1	0/40 Note 1	n/a	n/a	n/a	n/a	n/a	n/a	n/a	n/a
Biased HAST +130C/85%RH	96 Hours	N=39 Acc=0	N=39 Acc=0	n/a	n/a	n/a	n/a	n/a	n/a	n/a	n/a
High Temp Storage +150C	1000 Hours	N=39 Acc=0	N=39 Acc=0	n/a	n/a	n/a	n/a	n/a	n/a	n/a	n/a
Moisture Sensitivity Classification L3 Pb Free		N=11 Acc=0	N=11 Acc=0	N=11 Acc=0	N=11 Acc=0	N=11 Acc=0	N=11 Acc=0	N=11 Acc=0	N=11 Acc=0	N=11 Acc=0	N=11 Acc=0
UnBiased HAST +130C/85%RH	96 Hours	N=39 Acc=0	N=39 Acc=0	N=39 Acc=0	N=39 Acc=0	N=39 Acc=0	N=39 Acc=0	N=39 Acc=0	N=39 Acc=0	N=39 Acc=0	N=39 Acc=0
Temp Cycle +150/-65C	500 cycles	N=39 Acc=0	N=39 Acc=0	n/a	n/a	N=39 Acc=0	N=39 Acc=0	N=39 Acc=0	N=39 Acc=0	N=39 Acc=0	N=39 Acc=0

Note 1. Completed by extension from the already released assembly site - SRN110207